



# BAS16LS-Q

## High-speed switching diode

22 February 2021

Product data sheet

## 1. General description

High-speed switching diode, encapsulated in a leadless ultra small DFN1006BD-2 (SOD882BD) Surface-Mounted Device (SMD) plastic package with side-wettable flanks.

## 2. Features and benefits

- High switching speed:  $t_{rr} \leq 4$  ns
- Low leakage current
- Repetitive peak reverse voltage  $V_{RRM} \leq 100$  V
- Suitable for Automatic Optical Inspection (AOI) of solder joint
- Low capacitance
- Reverse voltage  $V_R \leq 100$  V
- Ultra small and leadless SMD plastic package
- AEC-Q101 qualified

## 3. Applications

- High-speed switching
- General-purpose switching

## 4. Quick reference data

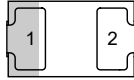

Table 1. Quick reference data

| Symbol   | Parameter             | Conditions  |     | Min | Typ | Max | Unit    |
|----------|-----------------------|---|-----|-----|-----|-----|---------|
| $I_F$    | forward current       | $T_j = 25$ °C   | [1] | -   | -   | 215 | mA      |
| $I_R$    | reverse current       | $V_R = 80$ V; $T_j = 25$ °C   |     | -   | -   | 0.5 | $\mu$ A |
| $V_R$    | reverse voltage       | $T_j = 25$ °C   |     | -   | -   | 100 | V       |
| $t_{rr}$ | reverse recovery time | $I_F = 10$ mA; $I_R = 10$ mA; $R_L = 100$ $\Omega$ ;<br>$I_{R(meas)} = 1$ mA; $T_{amb} = 25$ °C |     | -   | -   | 4   | ns      |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), 70  $\mu$ m single-sided copper, tin-plated and standard footprint.

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline   | Graphic symbol  |
|-----|--------|-------------|--|---|
| 1   | K      | cathode     |  <p>Transparent top view</p> <p><b>DFN1006BD-2 (SOD882BD)</b></p> |  <p>aaa-028035</p> |
| 2   | A      | anode       |  |   |

## 6. Ordering information

Table 3. Ordering information

| Type number | Package     |  |          |
|-------------|-------------|--|----------|
|             | Name        | Description  | Version  |
| BAS16LS-Q   | DFN1006BD-2 | Leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.65 mm pitch; 1 mm x 0.6 mm x 0.47 mm body | SOD882BD |

## 7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| BAS16LS-Q   | M8           |

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter                           | Conditions  |     | Min | Max | Unit |
|------------------|-------------------------------------|---|-----|-----|-----|------|
| $V_{RRM}$        | repetitive peak reverse voltage     | $T_j = 25\text{ °C}$  |     | -   | 100 | V    |
| $V_R$            | reverse voltage                     |   |     | -   | 100 | V    |
| $I_F$            | forward current                     |   | [1] | -   | 215 | mA   |
| $I_{FSM}$        | non-repetitive peak forward current | $t_p = 1\text{ }\mu\text{s}$ ; square wave; $T_{j(\text{init})} = 25\text{ °C}$ |     | -   | 4   | A    |
|                  |                                     | $t_p = 1\text{ ms}$ ; square wave; $T_{j(\text{init})} = 25\text{ °C}$          |     | -   | 1   | A    |
|                  |                                     | $t_p = 1\text{ s}$ ; square wave; $T_{j(\text{init})} = 25\text{ °C}$           |     | -   | 0.5 | A    |
| $I_{FRM}$        | repetitive peak forward current     | $t_p \leq 0.5\text{ ms}$ ; $\delta \leq 0.25$                                   |     | -   | 500 | mA   |
| $P_{\text{tot}}$ | total power dissipation             | $T_{\text{amb}} \leq 25\text{ °C}$  | [1] | -   | 345 | mW   |
|                  |                                     |   | [2] | -   | 645 | mW   |
| $T_j$            | junction temperature                |   |     | -   | 150 | °C   |
| $T_{\text{amb}}$ | ambient temperature                 |   |     | -55 | 150 | °C   |
| $T_{\text{stg}}$ | storage temperature                 |   |     | -65 | 150 | °C   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), 70  $\mu\text{m}$  single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), 70  $\mu\text{m}$  single-sided copper, tin-plated mounting pad for cathode 1cm<sup>2</sup>.

### 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol        | Parameter                                   | Conditions  |     | Min | Typ | Max | Unit |
|---------------|---|-------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | -   | -   | 360 | K/W  |
|               |   |             | [2] | -   | -   | 195 | K/W  |

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), 70  $\mu\text{m}$  single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 Printed-Circuit Board (PCB), 70  $\mu\text{m}$  single-sided copper, tin-plated mounting pad for cathode 1 $\text{cm}^2$ .

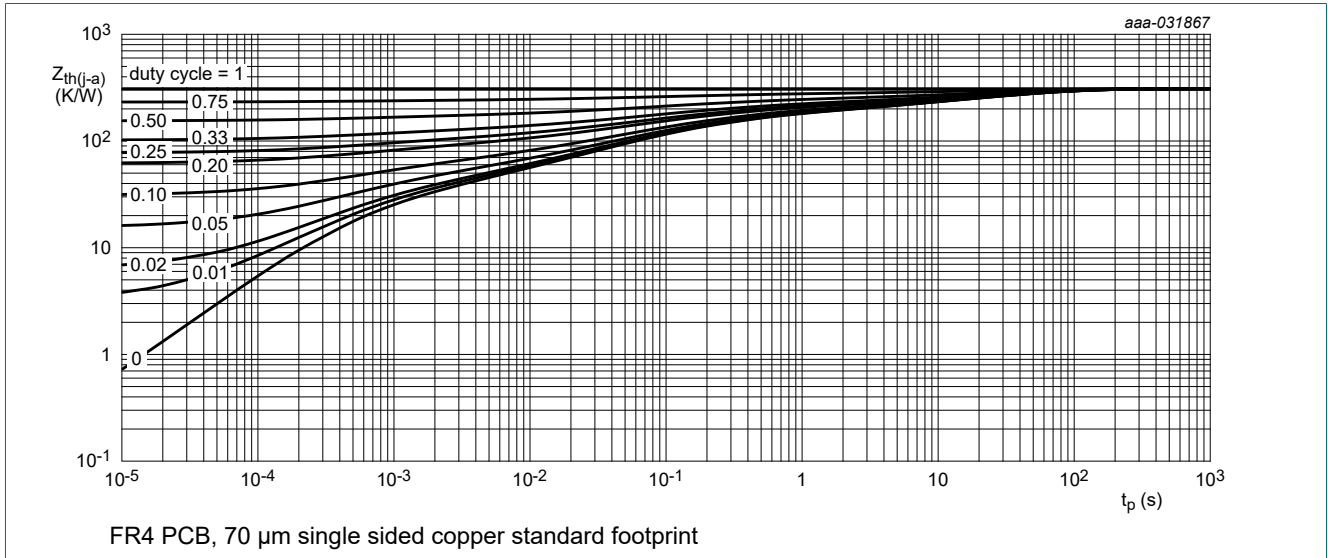


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

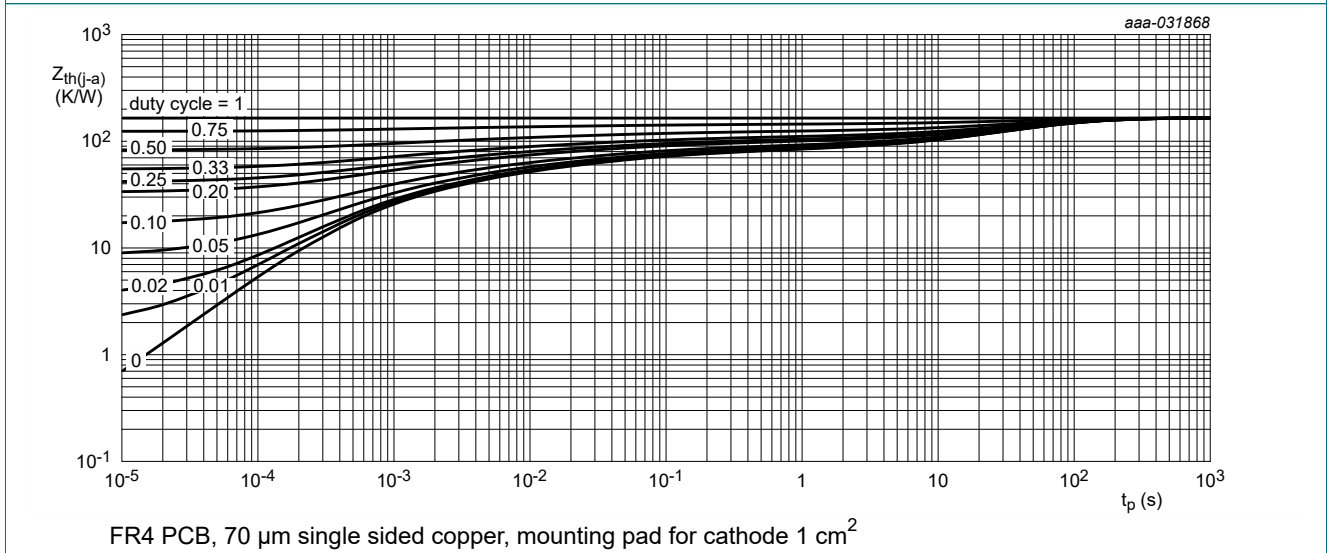
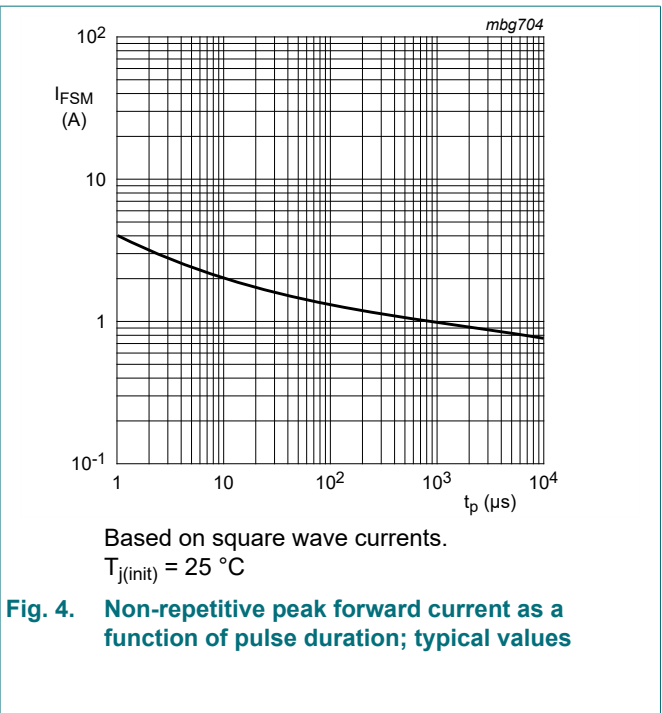
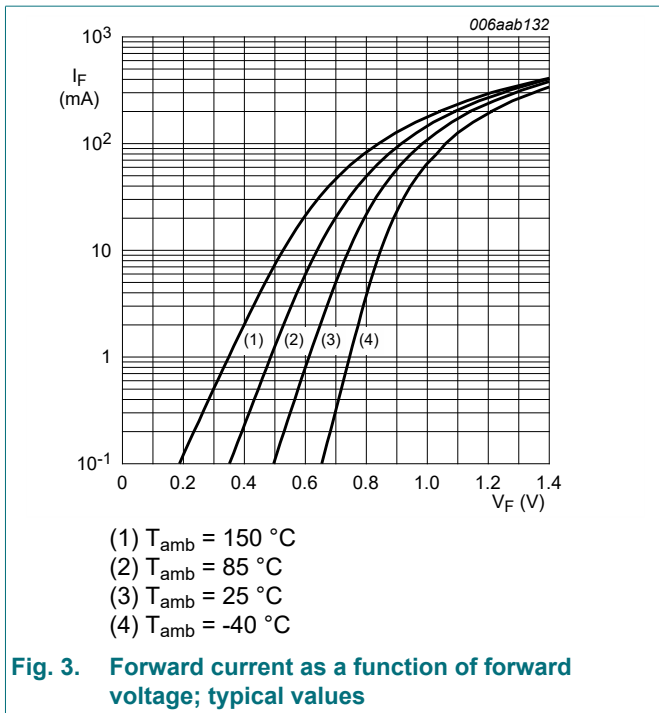


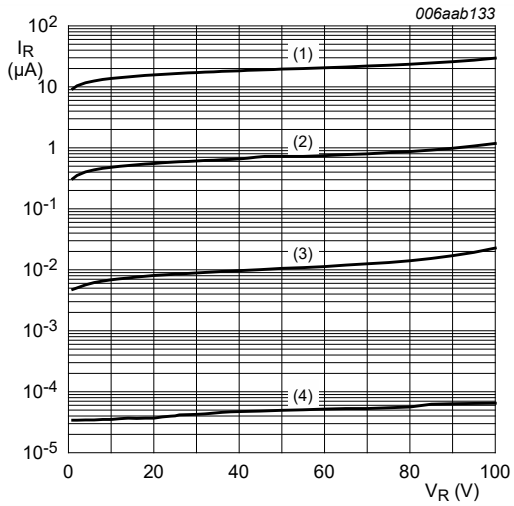
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

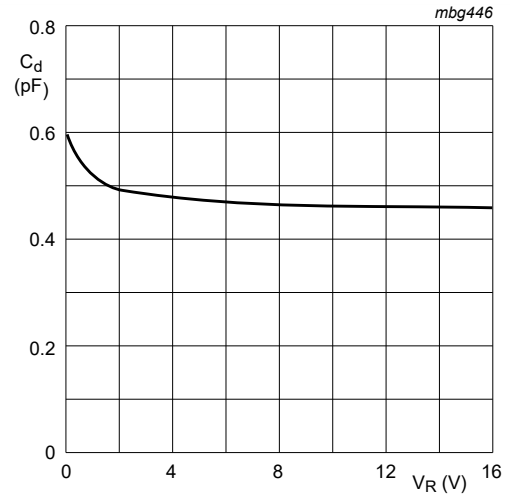
| Symbol           | Parameter                     | Conditions  | Min | Typ | Max  | Unit |
|------------------|-------------------------------|---|-----|-----|------|------|
| V <sub>F</sub>   | forward voltage               | I <sub>F</sub> = 1 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C  | -   | -   | 715  | mV   |
|                  |                               | I <sub>F</sub> = 10 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C   | -   | -   | 855  | mV   |
|                  |                               | I <sub>F</sub> = 50 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C   | -   | -   | 1    | V    |
|                  |                               | I <sub>F</sub> = 150 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C  | -   | -   | 1.25 | V    |
| I <sub>R</sub>   | reverse current               | V <sub>R</sub> = 25 V; T <sub>j</sub> = 25 °C   | -   | -   | 30   | nA   |
|                  |                               | V <sub>R</sub> = 80 V; T <sub>j</sub> = 25 °C   | -   | -   | 0.5  | μA   |
|                  |                               | V <sub>R</sub> = 25 V; T <sub>j</sub> = 150 °C  | -   | -   | 30   | μA   |
|                  |                               | V <sub>R</sub> = 80 V; T <sub>j</sub> = 150 °C  | -   | -   | 50   | μA   |
| C <sub>d</sub>   | diode capacitance             | V <sub>R</sub> = 0 V; f = 1 MHz; T <sub>amb</sub> = 25 °C   | -   | -   | 1.5  | pF   |
| t <sub>rr</sub>  | reverse recovery time         | I <sub>F</sub> = 10 mA; I <sub>R</sub> = 10 mA; R <sub>L</sub> = 100 Ω; I <sub>R(meas)</sub> = 1 mA; T <sub>amb</sub> = 25 °C | -   | -   | 4    | ns   |
| V <sub>FRM</sub> | peak forward recovery voltage | I <sub>F</sub> = 10 mA; t <sub>r</sub> = 20 ns; T <sub>amb</sub> = 25 °C  | -   | -   | 1.75 | V    |





- (1)  $T_{amb} = 150\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (4)  $T_{amb} = -40\text{ }^{\circ}\text{C}$

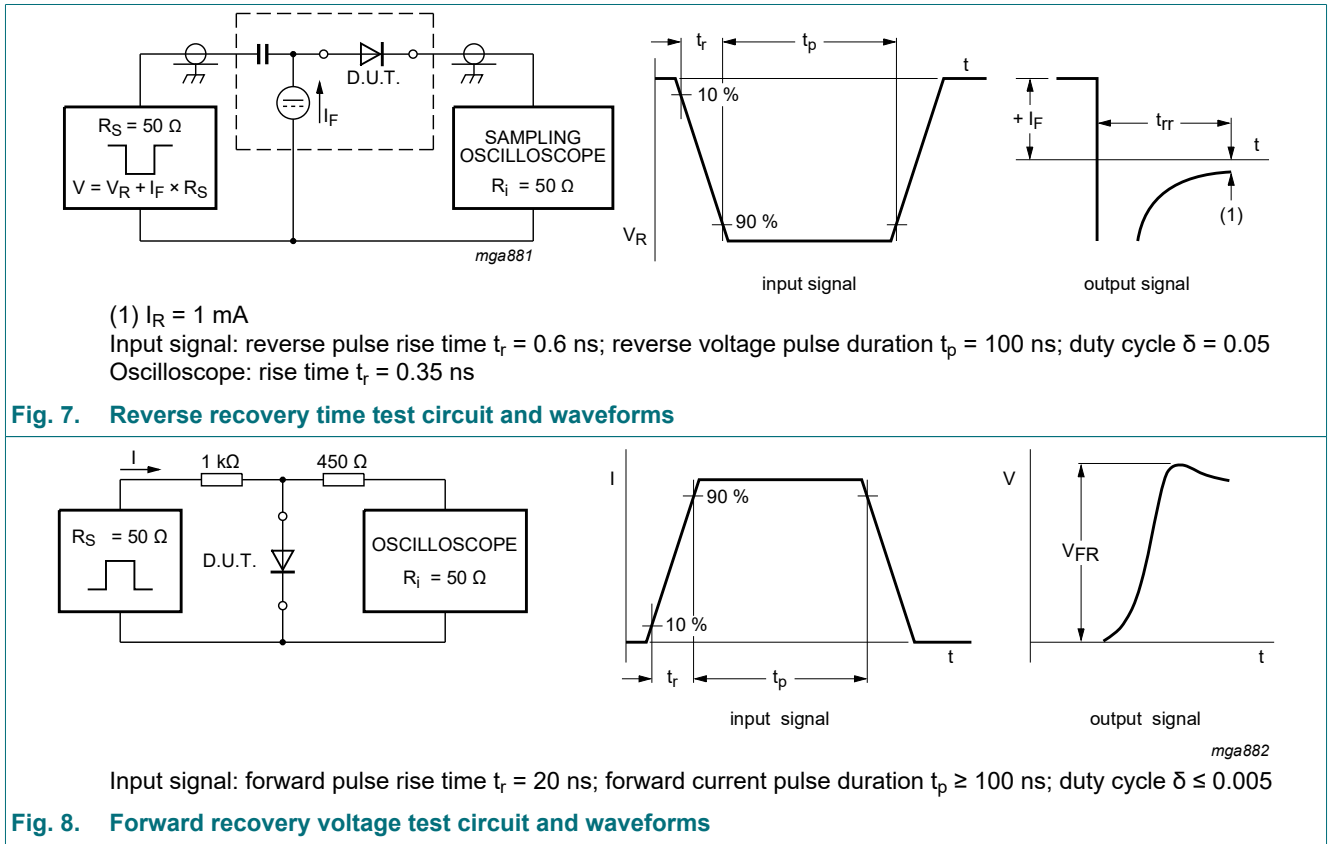
**Fig. 5. Reverse current as a function of reverse voltage; typical values**



$f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$

**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**

### 11. Test information



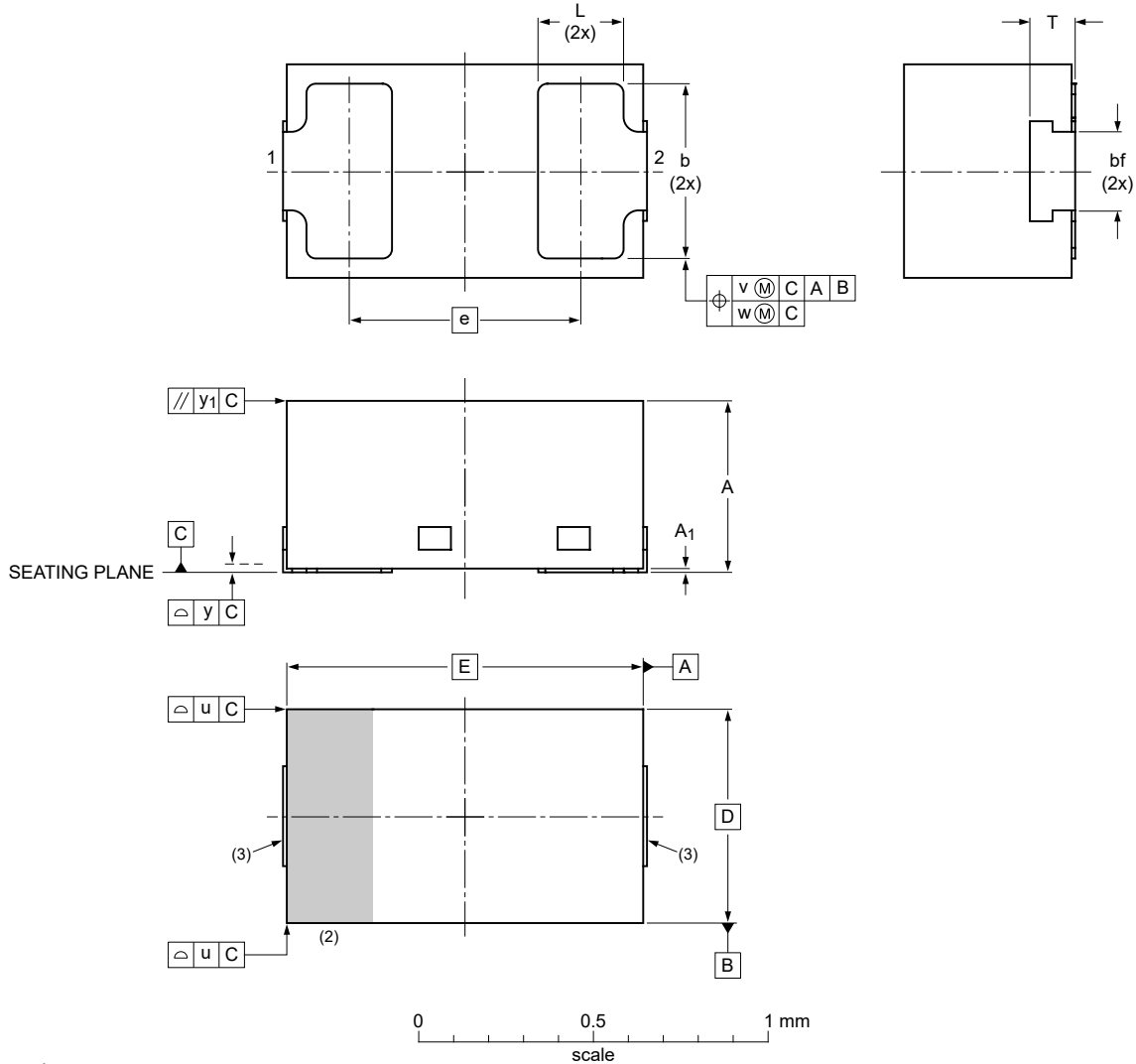
#### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline

**DFN1006BD-2** Leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals;  
0.65 mm pitch; 1 mm x 0.6 mm x 0.47 mm body

**SOD882BD**



**Dimensions**

| Unit | A <sup>(1)</sup> | A <sub>1</sub> | bf <sup>(1)</sup> | b    | D    | E    | e    | L    | T <sup>(1)</sup> | u    | v    | w    | y    | y <sub>1</sub> |
|------|------------------|----------------|-------------------|------|------|------|------|------|------------------|------|------|------|------|----------------|
| max  | 0.50             | 0.04           |                   | 0.55 |      |      |      | 0.30 | 0.22             |      |      |      |      |                |
| nom  | 0.47             |                |                   | 0.50 | 0.60 | 1.00 | 0.65 | 0.25 | 0.16             | 0.05 | 0.10 | 0.05 | 0.05 | 0.05           |
| min  | 0.44             |                | 0.20              | 0.45 |      |      |      | 0.22 | 0.10             |      |      |      |      |                |

**Note**

1. Dimension including plating thickness.
2. The marking bar indicates the cathode.
3. Solderable lead end, protrusion max. 0.02 mm.

sod882bd\_po

| Outline version | References |          |       |  | European projection | Issue date           |
|-----------------|------------|----------|-------|--|---------------------|----------------------|
|                 | IEC        | JEDEC    | JEITA |  |                     |                      |
| SOD882BD        |            | MO-343AA |       |  |                     | 20-06-22<br>20-06-23 |

**Fig. 9. Package outline DFN1006BD-2 (SOD882BD)**

### 13. Soldering

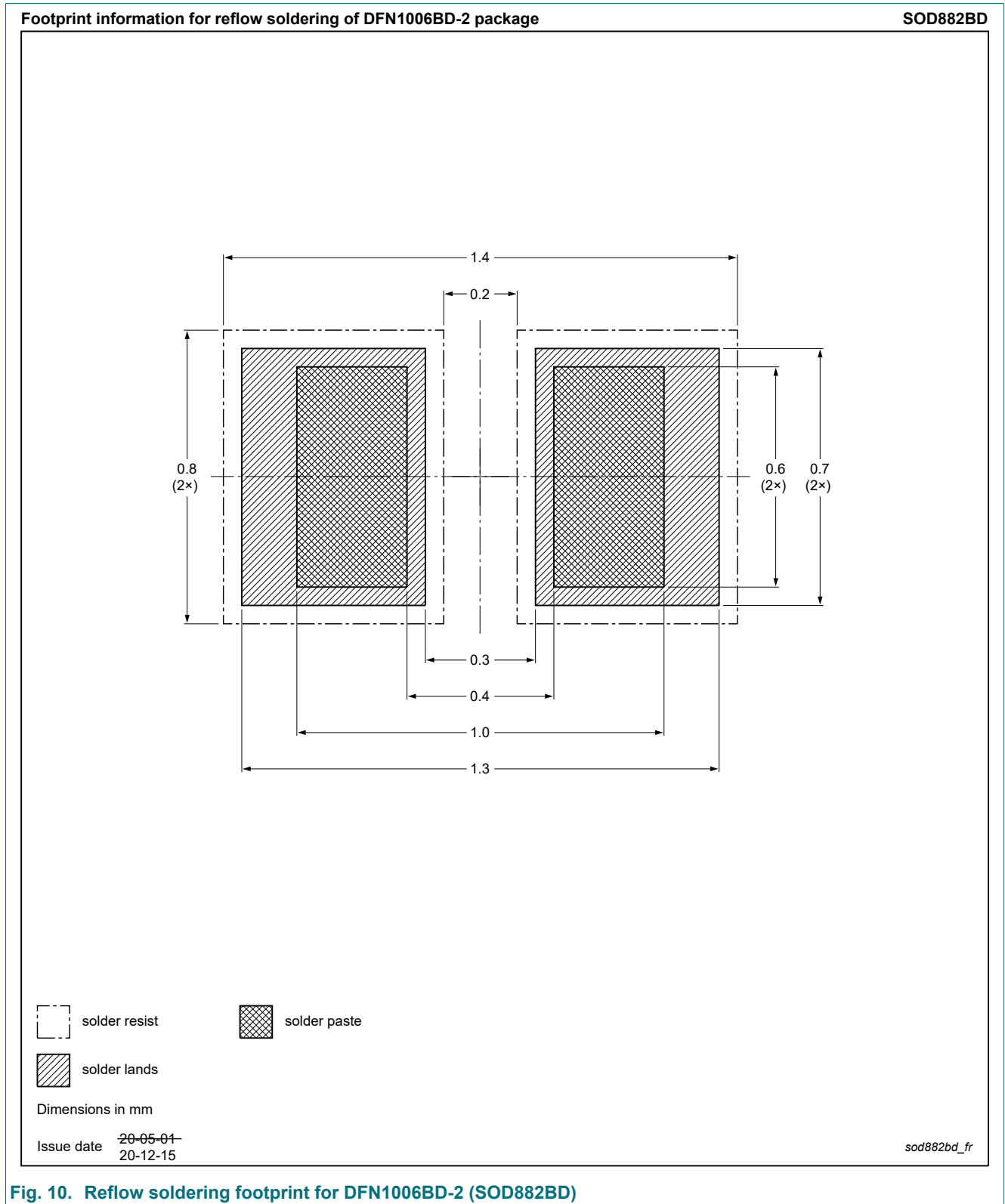


Fig. 10. Reflow soldering footprint for DFN1006BD-2 (SOD882BD)



## 14. Revision history

Table 8. Revision history

| Data sheet ID | Release date   | Data sheet status  | Change notice | Supersedes    |
|---------------|--|--------------------|---------------|---------------|
| BAS16LS-Q v.2 | 20210222   | Product data sheet | -             | BAS16LS-Q v.1 |
|               | • Changed package outline from minimized to standard |                    |               |               |
| BAS16LS-Q v.1 | 20210209   | Product data sheet | -             | -             |

## 15. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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